

Product Description

Shin-Etsu's G-776 thermal interface grease is a high reliability product that offers high resistance to pump-out, creep, and oil separation. G-776 also offers high thermal conductivity and excellent electrical properties. G-776 is a solvent diluted grease which allows for both ease of use and low oil bleed (after solvent evaporation).

Product Features

- High thermal conductivity
- Excellent electrical properties
- Ease of use and low oil bleed

Typical Applications

- Semiconductor elements and heat sinks requiring high reliability

Typical Properties

Type	Thermal Grease
One/Two Component	One
Low Molecular Weight Siloxane Stripped?	Y
Color	White
Density @ 23C (g/cm ³)	2.90
Viscosity (Pa·s)	60
Penetration (1/10mm)	354
Dielectric Strength (kV/mm)	11.6
Thermal Conductivity (W/m·K)	1.30
% Volatile Content	3.10
Usable Temp. Range (C)	-40 to +200

Note: Values are not for specification purposes.

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